Special Issue

Advanced Optimization Methods for the Design of Electromagnetic Devices

Message from the Guest Editors

This Special Issue aims to present a collection of scientific manuscripts covering the theoretical and practical aspects associated with optimization methods for electromagnetic devices and systems. The state-of-the-art and any emerging developments in this field are welcome. Topics may include, but are not limited to, the following:

- Improved/advanced intelligent optimization algorithms
- Surrogate models and design of experiment techniques
- Multi-objective optimization methods
- Multi-level optimization methods
- Multidisciplinary optimization methods
- Reliability-based optimization methods
- Robust optimization methods
- Parallel computing and optimization
- Optimization methods based on cloud computing technologies
- Al-based optimization methods for electromagnetic devices and systems

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Deadline for manuscript submissions

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multidimensional network.

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